

Amendments to the Claims

Claim 1 (**Currently Amended**) A polishing apparatus comprising:
a polishing table having a polishing surface;
a top ring adapted to hold and rotate a substrate having a semiconductor device thereon and
press a surface of the substrate against said polishing surface to polish the surface of the substrate;
a stationary section;
at least one optical measuring device disposed on said stationary section adjacent to an outer
peripheral portion of said polishing table and below said polishing surface of said polishing table, said
at least one optical measuring device being operable to measure a thickness of a layer formed on the
surface of the substrate; and
at least one notch formed in said outer peripheral portion of said polishing table, said at least
one notch allowing light emitted from said at least one optical measuring device to pass therethrough
and be incident on the surface of the substrate and allowing light reflected from the surface of the
substrate to pass therethrough and be incident on said at least one optical measuring device, wherein
said top ring is swingable ~~between an inner area and an outer area on said polishing table~~ so that the
light emitted from said at least one optical measuring device is incident on ~~a position ranging from~~
~~an outer circumferential edge to a central portion of the substrate~~ at least a central portion of the
substrate.

Claims 2 and 3 (**Canceled**)

Claim 4 (**Previously Presented**) A polishing apparatus according to claim 1, wherein when
said top ring is swung to a maximum, an area of the substrate which projects outward beyond an
outer circumferential edge of said polishing table is not more than 40% of an entire area of the surface
of the substrate being polished.

Claim 5 (**Previously Presented**) A polishing apparatus according to claim 1, further comprising a nozzle operable to supply a cleaning liquid to said at least one optical measuring device.

Claim 6 (**Canceled**)

Claim 7 (**Currently Amended**) A polishing apparatus comprising:
a polishing surface having a notch formed in an outer peripheral portion thereof;
a top ring for holding and rotating a substrate having a semiconductor device thereon and pressing a surface of the substrate against said polishing surface to polish a layer formed on the surface of the substrate; ~~and~~
a stationary section; and
a thickness measuring device disposed on said stationary section for measuring a thickness of the layer formed on the surface of the substrate, said thickness measuring device being arranged so that ~~the layer, being polished, on the surface of the substrate,~~ said notch of said polishing surface[,] and said thickness measuring device are aligned with each other,
wherein said top ring is swingable so that a central portion of the substrate moves onto said notch of said polishing surface.

Claim 8 (**Currently Amended**) A polishing apparatus according to claim 7, further comprising a rotatable polishing table ~~and a stationary section,~~
wherein said polishing surface is mounted on said rotatable polishing table ~~and said thickness measuring device is disposed on said stationary section.~~

Claim 9 (**Canceled**)

Claim 10 (**Previously Presented**) A polishing apparatus according to claim 7, wherein said polishing surface has at least one additional notch, said notch and said at least one additional notch being formed in said outer peripheral portion of said polishing surface.

Claim 11 (**Previously Presented**) A polishing apparatus according to claim 8, wherein said polishing surface has at least one additional notch formed in said outer peripheral portion thereof, said notch and said at least one additional notch forming a plurality of notches, and

wherein said top ring moves the substrate so that a central portion of the layer is positioned on one of said plurality of notches of said polishing surface when said thickness measuring device measures the thickness of the layer.

Claim 12 (**Currently Amended**) A polishing apparatus according to claim 8 [[9]], further comprising a nozzle for supplying a cleaning liquid to said thickness measuring device.

Claim 13 (**Currently Amended**) A polishing apparatus according to claim 8 [[9]], wherein the layer on the surface of the substrate comprises an insulating layer.

Claim 14 (**Currently Amended**) A polishing apparatus according to claim 8 [[9]], wherein said thickness measuring device comprises an optical measuring device.

Claim 15 (**Previously Presented**) A polishing apparatus according to claim 12, wherein said thickness measuring device comprises an optical measuring device.

Claims 16-21 (**Canceled**)

Claim 22 (**New**) A polishing apparatus according to claim 1, wherein said top ring is swingable between an inner area and an outer area on said polishing table.

Claim 23 (**New**) A polishing apparatus according to claim 7, wherein said top ring is swingable between an inner area and an outer area on said polishing table.

Claim 24 (New) A polishing apparatus comprising:
a polishing surface having a notch formed in an outer peripheral portion thereof;
a top ring for holding and rotating a substrate having a semiconductor device thereon and pressing a surface of the substrate against said polishing surface to polish a layer formed on the surface of the substrate;
a stationary section; and
a thickness measuring device disposed on said stationary section for measuring a thickness of the layer formed on the surface of the substrate, said thickness measuring device being arranged so that said notch of said polishing surface and said thickness measuring device are aligned with each other,
wherein said top ring is swingable on said polishing table so that a central portion of the substrate moves onto said notch of said polishing surface.

Claim 25 (New) A polishing apparatus according to claim 24, wherein said top ring is swingable between an inner area and an outer area on said polishing table.